IN THE SPECIFICATION:

Please amend the specification as follows:

Please amend paragraph number [0047] as follows:

[0047] The lower opening 44 has a width 48 (FIG. 4) equivalent to about two (2) to about ten (10) sphere diameters 28. Thus, for conductive spheres 12 having a diameter 28 of 1.0 mm, the lower opening may have a width 48 of about 0.2 cm. to about 1.0 cm.

Please amend paragraph number [0048] as follows:

[0048] As shown in drawing FIG. 4, the hopper 50A has a lower surface 60 which is spaced from the upper surface 38 of the stencil plate 30 by a short distance 62. Distance 62 is less than one-half (and preferably less than one-third) of the-ball sphere diameter 28, and the stencil plate 30 and hopper 50A may even be in contact. The hopper 50A is controlled to reversibly move across through-hole pattern 32 in direction 68 from a first position 64 beyond one side of the through-hole pattern 32 to a second position 66 beyond the other side of the pattern, dropping conductive spheres 12 into each through-hole 34, and thereby onto each bond pad 14 directly below.